ABT,Applications

ABT Applications

Literature Number: SNOA005

National Semiconductor

ABT Applications

Avoiding Bus Contention

ABT devices typically disable (to high impedance) faster than they enable (to active state) and therefore offer an inherent way to minimize bus contention. System designers must be aware of the effects of bus interface device exposure to contention. Some advice is offered in the following discussion.

Ideally the system designer should insure that the disabling signal to the active driver always precedes the enabling signal to the next driver to insure minimum contention; i.e., t_{SETUP} time disable-to-enable should be a positive number. If the interface devices on the bus (as NSC ABT devices typically do by design) exhibit disable times (t_{PHZ}/t_{PLZ}) quicker than enable times (t_{PZH}/t_{PZL}), then the t_{SETUP} time disable-to-enable can be reduced to zero or slightly negative and not cause significant contention.

The typical t_{SETUP} time is approximated from the typical enable/disable time specs: t_{SETUP} disable-to-enable = $t_{PLZ} - t_{PZH}$ or = $t_{PHZ} - t_{PZL}$; whichever yields the most positive number governs. Obviously if disable time is larger than enable time then t_{SETUP} is a positive time. Worst case t_{SETUP} is calculated from the min/max enable times: t_{PLZ} (max) − t_{PZH} (min) or t_{PHZ} (max) − t_{PZL} (min) and will always yield a safer positive number.

Data taken on a '245 function in a bus contention test fixture may be helpful to illustrate the effects of varying the t_{SETUP} from a value which caused no contention to values which caused significant contention in *Figures 1, 2* and *Figure 3*.

No reliability data to calculate fit rates to support a degree of contention resilience is offered at this time. Deliberate contention is not recommended. For instance a designer should be rightly concerned about the magnitude of current that can flow when a 64 mA (min) bus interface sink (I_{OL}) stage contends with a −225 mA (max) source (I_{OS}) stage for a large overlap time period with multiple outputs switching. Particularly true for the newer bus interface parts like ABTC which have I_{OS} specifications more negative than the −225 mA max.

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Avoiding Bus Contention (Continued)

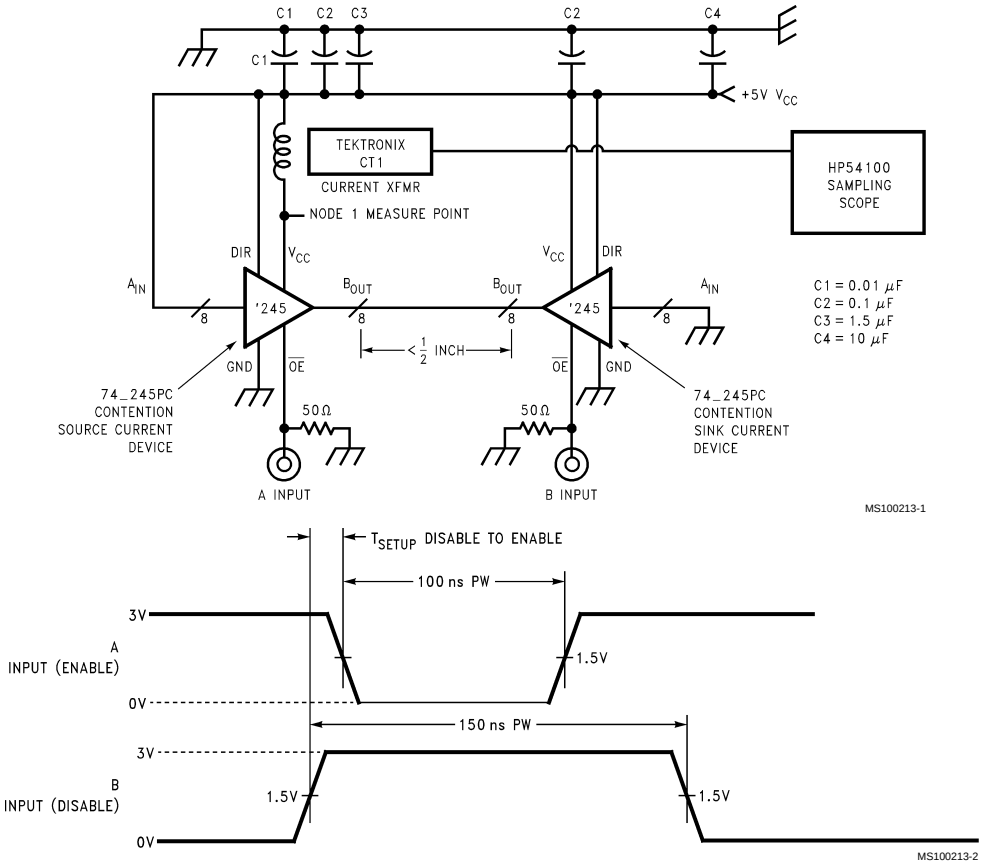
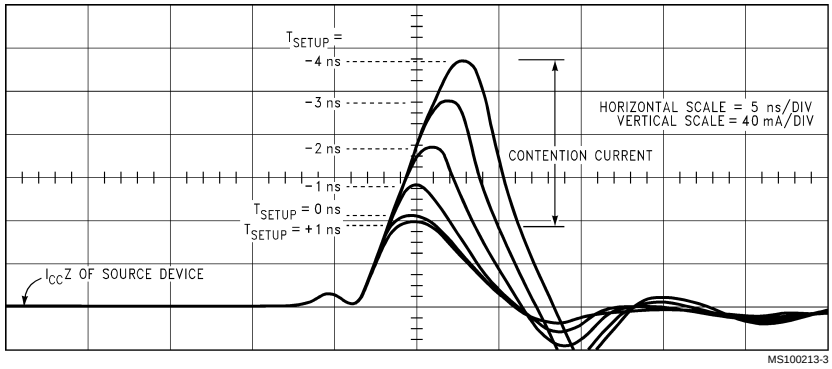


FIGURE 1. '245 Function Bus Contention Test Fixture

Procedure: Adjust t_{SETUP} by varying the delay of B pulse. Monitor contention current of OR-tied B outputs at node 1.



At T_{SETUP} = +1 ns, there is no contention current, merely normal capacitive charging during LH transition. Bus contention is measured with 8 outputs switching in phase on both devices. This example used the 74F245PC, with the monitor on pin 18, B_{OUT}.

FIGURE 2. Bus Contention Current

Avoiding Bus Contention (Continued)

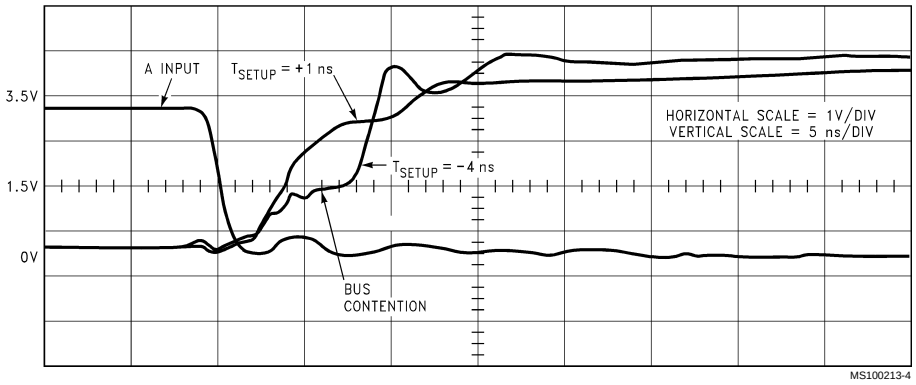


FIGURE 3. Output Response in Bus Contention Test Fixture

Floating Input Considerations for BiCMOS Design

ABT INPUT STRUCTURE DESIGN

Although the inputs of a BiCMOS device operate with TTL voltage levels, it is important to understand that the circuitry is built primarily with CMOS stuctures. *Figure 4* shows the basic structure of a typical ABT input. The nature of the ABT input operation is very similar to that of Advanced CMOS devices. There is minimum power dissipated due to I_{CC} when the input is in either the High or Low logic state; since only one structure will be turned on at a time. Special considerations for power dissipation must be made however, when the inputs of a BiCMOS device are being subjected to an undefined level — such as that on a TRI-STATE® system bus.

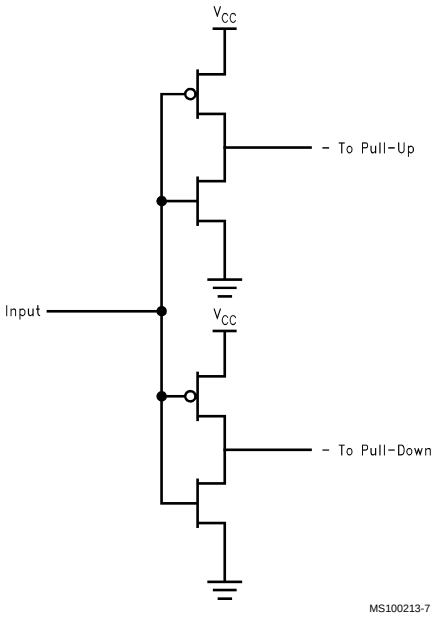


FIGURE 4. Simplified ABT Input Structure Diagram

EFFECTS OF FLOATING INPUTS

Typically, a number of bi-directional transceivers will be connected in parallel with each other between two system busses; as in *Figure 5*. Before data can be transferred from one bus to the other, the devices connected to the receiving bus will have their outputs disabled for some period of time prior to the appearance of valid data on the driving bus. This is necessary to prevent data corruption and contention between busses. While the outputs are disabled, there is minimum concern for the effects of I_{CC} on power dissipation — the output enable circuitry is designed to interact with the input stages to effectively cause them to act as open circuits to V_{CC} and ground. Floating inputs become a concern when the outputs are enabled and there are a number of inputs that remain connected to a TRI-STATE system bus for a period of time.

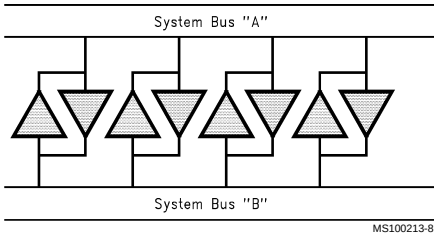


FIGURE 5. Bi-Directional Bus Transceivers

During the time that the bus is inactive, TRI-STATE leakage currents will charge the lines to some voltage level within the input threshold region of the device. In the threshold region, and with the outputs enabled, the output pull up and pull down stages may be partially turned on simultaneously. This results in significant flow of I_{CC} through the input structure to ground. This current is orders of magnitude larger that the typical leakage currents I_{IH} or I_{IL}. Given that this is occurring on a number of transceivers located on the same physical device, the problem is compounded. Permanent damage or long term reliability effects on the device may become a concern.

Floating Input Considerations for BiCMOS Design (Continued)

SYSTEM DESIGN CONSIDERATIONS

In a BiCMOS system design, floating inputs can be dealt with using one of two methods. If the amount of time that the bus is going to be inactive is very short (on the order of microseconds), then the issue can be disregarded. Because this time can be unpredictable due to normal variations in operation the more commonly used approach will be to ensure that the system bus is always going to be at a valid voltage level. This is accomplished with the use of a pull up resistor to terminate the bus line. It is recommended that a 1k to 10k resistor be connected between the device input and V_{CC}. Although additional considerations will be made for DC power dissipation by the termination network, pull up resistors will ensure an added level of protection against the effects of floating device inputs.

NATIONAL'S ABT DESIGN CONSIDERATIONS

National has considered the issue of floating inputs during design of the ABT product family. 8-bit and 16-bit '244 and '245 functions have been designed with additional protection against the effects of floating inputs. In previous discussion, we examined that when a device input is left at some voltage level near the threshold, it is possible for both the input pull up and pull down structures to be partially turned on and conducting I_{CC} to ground. Depending on the number of inputs at threshold, and the time that they are in the threshold region, the results could be adverse to both the device and the system. National Semiconductor has designed the input structures of their ABT buffers and transceivers such that the pull up and pull down structures will completely shut off while the input voltage is within the threshold region. This is accomplished by controlling the characteristics of the pull up and pull down structures such that there is an imbalance between their turn on voltages. This prevents simultaneous conduction of the input structures with the presence of a threshold voltage at the input. *Figure 6* demonstrates the shutdown of the input structures between the input voltages of 1.2V and 1.4V.

SUMMARY

Because CMOS structures are incorporated into the ABT input circuitry, considerations must be made for the resulting effects upon device inputs that are connected to a bi-directional TRI-STATE system bus. If these lines are not terminated to a valid input level, the result will be I_{CC} current flow to ground — compounded by the number of inputs that are exposed to threshold levels. The power being dissipated internally to the device may have an effect on long term device and system performance; or may result in a catastrophic failure. Standard system design practice suggests that floating input pins be terminated with a pull up resistor to V_{CC}. This practice — in conjunction with National's robust ABT input design — will ensure that the system designed with ABT logic devices will operate efficiently and reliably.

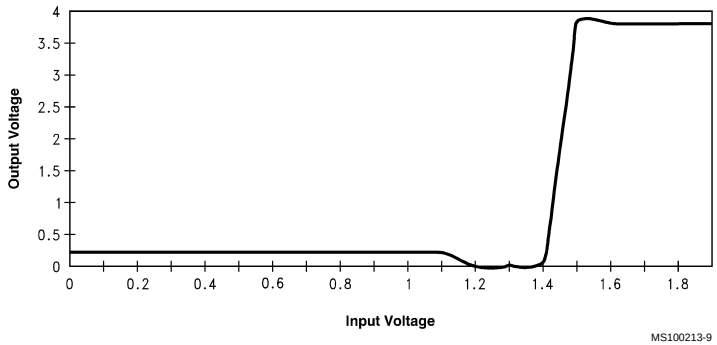


FIGURE 6. Input Characteristics Demonstrating Shutdown at Threshold Levels

Power Down Characteristics

Power-down characteristics provide the system designer's with an understanding of the loading effects from a device when the device power supply is at 0.0V. The device's powered-down characteristics effect the system bus or backplane in a number of ways and can be characterized by its input and output capacitance and current loading. The measured parameters that provide the designers with loading information include; C_{IN}/C_{OUT}, input/output capacitance; IZZ, tri-stateable output power-down current loading; VID, input power-down current loading.

A device's input and output capacitance define the effective bus and backplane loading through the charging and discharging of the interface pins. ABT devices have typical capacitance values of 5 pF for input pins and 9 pF for output pins, while I/O pins have a typical value of 11 pF. National tests capacitance in accordance with the procedures outlined in the MIL-STD-883, method 3012.

The power-down leakage characteristics of an ABTC device provide the effects of current loading on a bus or backplane. Typically, loading leakages in the +200 µA range begin to effect the V_{OH}/V_{OL} levels in a backplane application. The VID and IZZ curves in *Figures 4, 5* illustrate the loading effects on the backplane over a range of backplane voltages from 0.0V to 5.5V while the power supply is kept at 0.0V.

— VID

VID is a voltage that is measured on an input pin at a current loading of 1.9 µA in a power off condition such as when V_{CC} and the non-measurement pins are at 0.0V.

Power Down Characteristics

(Continued)

The curve of VID vs IID in *Figure 7* shows the current leakage of a typical ABT input pin. ABT inputs typically limit loading leakage to <1.9 µA over an input voltage range from 0V to 5.5V at room temperature.

— IZZ

IZZ is a current that is measured on an output pin at a voltage of 5.5V during a power off condition such as when V_{CC} and the non-measurement pins are at 0.0V.

The curve of VZZ vs IZZ in *Figure 8* shows the current leakage of a typical ABT input/output (I/O) pin and how it loads a bus or backplane over a range of bus voltages from 0.0V to 5.5V. I/O pin configurations exhibit combined current characteristics from components of the input circuitry and output circuitry. ABT I/O pins specify maximum loading leakage at 100 µA with a typical loading leakage at 3 µA at room temperature.

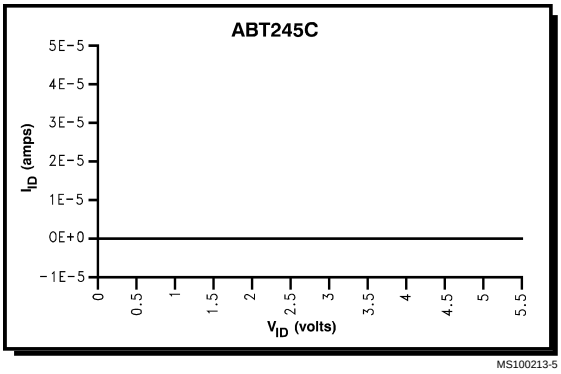


FIGURE 7.

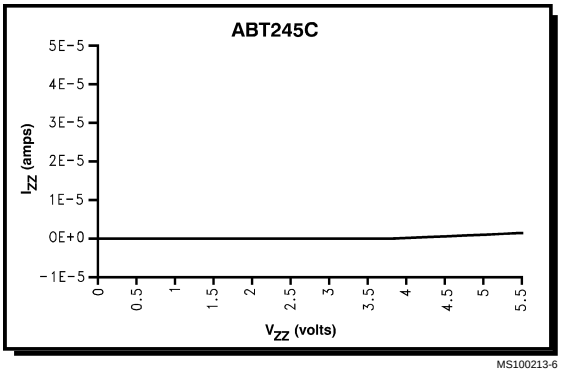


FIGURE 8.

Models

National Semiconductor in conjunction with Quad Design, offers SPICE and TLC models for the system designer. Each model provides information on parameters that speed design-in activities. The description, use and availability of the two types of models is outlined below.

SPICE

Description: The SPICE input files are valid representations of the input, output, I/O and associated circuitry used on the logic device modeled. The circuit and device models were designed and verified using SPICE 2G6. National Semiconductor makes no guarantee that identical results will be produced by other hardware/software combinations. Proper execution of these models is not guaranteed if any changes are made to its files.

File Name Conventions:

FFFDDDDS.TTT FFF — family code (ABT)

DDDD — device designation (245)

S — step revision of model file

TTT — valid temperature of file with a preceding m representing minus

Exceptions may be seen in file names such as 16 bit devices.

Use: While SPICE simulation input files may be a useful and beneficial tool to the system designer for the purpose of modeling bus loading and DC drive characteristics, and due

Models (Continued)

to the complexities indigenous to the modeling of transient phenomenon, National Semiconductor recommends that simulated results be supported by laboratory characterization prior to making final judgments regarding device transient performance.

The input files incorporate single bit models over cold, room and hot die temperatures as well as package models.

Availability: If an ABT product is orderable, the SPICE models is available through the Applications Engineering Group at Fairchild Semiconductor.

333 Western Avenue

South Portland, Maine 04106

Telephone: (800) 341-0392

Or check the website at www.fairchildsemi.com.

TLC

Description: Transmission Line Calculator, (TLC) Models provide the system designer with transmission line characteristics such as signal quality. TLC predicts ringing, undershoot and overshoot, performs automated analysis of entire PCB designs and offers accurate delay data for ABTC products. National provides AC, DC and capacitance characteristics for the model which Quad Design compiles and makes available for customers. The characteristics are generated either empirically or from SPICE simulations. The AC characteristics include output edge rate and the DC characteristics include output drive capacity and input/output leakage data.

Use: The TLC models are most often used for signal analysis in PCB designs. TLC program features include predictability of ringing, non-incident switching, undershoot, overshoot, and time delay for networks of arbitrary topology and construction. The program may also be used to evaluate network loading and termination strategies. Additionally, TLC provides users with critical clock and backplane signal analysis tools as well as tools for viewing the effects of tristate bus contention.

Availability: TLC models on orderable product may be obtained by contacting:

Quad Design

1385 Del Norte Road

Camarillo, California 93010

Telephone: (805) 988-8250

FAX: (805) 988-8259

Measurement Based Digital Signal Integrity Models

Zeelan Technology, Inc. offers a library of digital signal integrity models that are based on measurements from actual parts. As CPU speed increases, there is an increasing need for design tools to predict circuit behavior by simulation. Zeelan's models and libraries allow designers to identify digital signal integrity problems based on the final layout of the circuit board during the design phase. Since the digital signal integrity problems of the physical layout are identified before the fabrication of the circuit card, design changes and optimization can be made before building a prototype. The results are fewer prototypes during the development process with a saving in time and reduction of effort. The outcome is a product with the system operating at the maximum level, confidence in the system's reliability and end user satisfaction with the system's performance.

To achieve these results from simulation, digital designers need models that represent the digital part. Zeelan's process involves measurement of the actual part's parameters to derive realistic models and then formatting the models for specific requirements of individual simulators including Mentor Graphics, Quad Design, Greenfield, Quantic Laboratories and Intergraph. The information in each of Zeelan's MasterModels™, designates the specific manufacturer's part number, pin out and pin names. To ease the installation, Zeelan software models are recorded on the designer's media of choice and are ready to load and run.

Zeelan's models are the answer to three fundamental needs. Traditional libraries are based on a range of values from data books instead of a specific value, estimates when no data is available (rise and fall time) and generic models to represent all the parts in a logic family for all manufacturers. Available models do not provide the clarity designers need to represent digital parts. Also, today's digital designs need models that account for differences between the same part type from differeent manufacturers and the high frequency analog behavior of digital parts. In response to these needs, Zeelan provides realistic models for individual National Semiconductor digital parts that result from measurements with actual parts.

The Zeelan Library for National Semiconductor can be combined with Zeelan's microprocessor libraries to provide designers with libraries for the total system design with Pentium™ Processor, Intel® 486SX™ 33 MHz, Intel® SL 486DX2, Motorola 68040, 68EC040 and 68LC040 microprocessors.

Availability: Measurement based digital signal integrity models on released devices may be obtained by contacting:

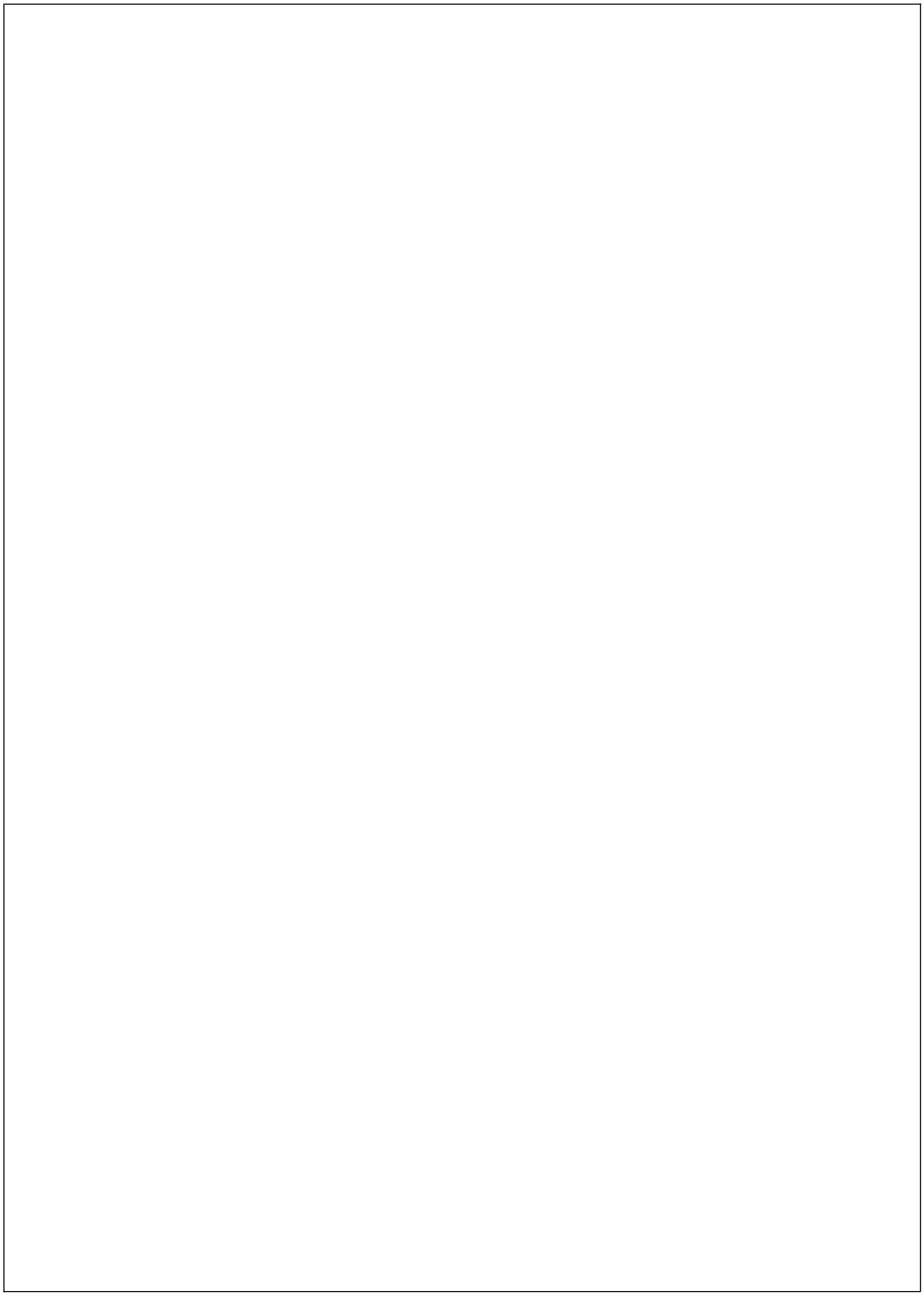
ZEELAN TECHNOLOGY, INC.

10550 S.W. Allen Blvd., Suite #108,

Beaverton, OR 97005

Telephone: (503) 520-1000

Request the 74/54 National Semiconductor Digital MasterModel™ Library and Microprocessor MasterModel™ Library in the simulator format of your choice.



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National Semiconductor Asia Pacific Customer Response Group
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